

REMARKS/ARGUMENTS

Vias through a substrate are well known in the art and are adequately described on page 3, lines 3-6 of the specification as "connecting conductive electrodes such as electrodes 13, 14, 15 on the top of substrate 10 to respective BGA solder balls on the bottom of the substrate, such as BGA solder balls 16, 17 and 18." Thus, one of ordinary skill in the art will understand how to practice the disclosed invention.

In order to fully comply with the Office Action, a schematic representation of a cross-section of a via has been added to Figure 1, as an example. Thus, the application is now in condition for allowance.

No new matter has been added by the addition of the schematic representation of the via to Figure 1, which is adequately described on page 3, lines 3-6 of the specification.

Applicants respectfully request that the replacement figure be entered.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 5, 2003:

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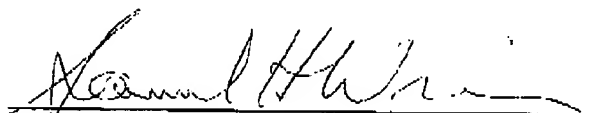
Name of applicant, assignee or  
Registered Representative

  
Signature

August 5, 2003

Date of Signature

Respectfully submitted,

  
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